

PRODUCT SPECIFICATION

DOCUMENT NO. ENS000168590						
DESCRIPTION	DRAWN BY	DESIGNED BY	CHECKED BY	APPROVED BY		
MLVS1206LDG Series	Sandy	JamesTeng	JamesTeng	Shawn Yeh		





1. Scope

- (1) RoHS compliant
- (2) Meet IEC 61000-4-5 standard
- (3) SMD type zinc oxide based ceramic chip
- (4) Insulator over coat keeps excellent low and stable leakage current
- (5) Quick response time (<0.5ns)
- (6) High transient current capability
- (7) High reliability
- (8) Compact size for EIA1206

Applications

Applications for Mother Board and Notebook, Cellular Phone, PDA, handheld device, DSC, DV, Scanner, and Set-Top Box etc.

Suitable for Push-Button, Power Line and Low Frequency single line over voltage protect.

2. Explanation of Part Number

<u>MLV</u>	<u>S</u>	<u>1206</u>	<u>L</u>	<u>04</u>	<u>202</u>	<u>DG</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)

- 1. Multilayer varistor
- 2. Type: S=single
- 3. Size
- 4. Lead free series
- 5. Max. AC voltage
- 6. Typical Capacitance: "202" means 20×10²
- 7. Inpaq Control Code

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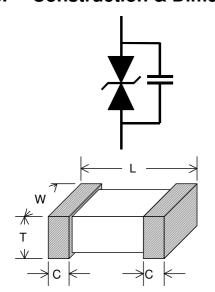
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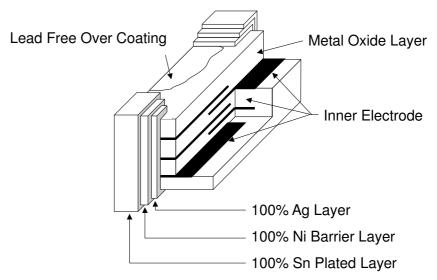
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3. Construction & Dimension





Unit: mm	1206
L	3.20±0.3
W	1.60±0.2
Т	0.80±0.1
С	0.50±0.25

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4. Part ratings and characteristics

4.1. Ratings (25 °C for characteristics, 125 °C for maximum ratings)

	Working voltage		Varistor	Clamping		Peak	Transient
			voltage	Voltage	Capacitance	current	energy
Symbol	V _{RMS}	V _{DC}	Vv	Vc	Ср	i _{max}	W _{max}
Units	Volts	Volts	Volts	Volts	pF	Amps	Joules
Units	(Max.)	(Max.)	VOILS	(Max.)	(Typical)	(Max.)	(Max.)
Test Condition		< 10 μΑ	1mA DC	1 A 8/20μs	1KHz	8/20µs	10/1000μs
MLVS1206L04202DG	4	5.5	8~14	25	2000	200	0.3
MLVS1206L11661DG	11	14	18~22	38	660	100	0.5
MLVS1206L11841DG	11	14	18~22	36	840	200	0.5
MLVS1206L14901DG	14	16	22~28	42	900	200	0.6
MLVS1206L17781DG	17	22	25~32	48	780	200	0.3
MLVS1206L20601DG	20	26	29.7~37.3	58	600	200	0.7
MLVS1206L25651DG	25	31	36~44	69	650	200	1
MLVS1206L30601DG	30	38	45~55	81	600	200	1.1
MLVS1206L35231DG	35	45	54~62	108	230	200	1.1
MLVS1206L40221DG	40	56	66~82	110	220	200	1
MLVS1206L50251DG	50	65	77~93	138	250	100	0.5
MLVS1206L60121DG	60	85	104~126	168	120	100	0.7

- V_{RMS} Maximum AC operating voltage the varistor can maintain and not exceed 10μA leakage current
- V_{DC} Maximum DC operating voltage the varistor can maintain and not exceed 10μA leakage current
- V_V−Voltage across the device measured at 1mA DC current. Equivlent to Vb, "Breakdown Voltage".
- Vc Maximum peak voltage across the varistor measured at 8/20us waveform and 1A pulse current
- Cp Device capacitance measured with zero volt bias 1Vrms.
- i_{max} Maximum peak current which may be applied with 8/20us waveform without device failure
- W_{max} Maximum energy that may be dissipated with the 10/1000us waveform without device failure

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5. General electrical specifications

5.1. General technical data

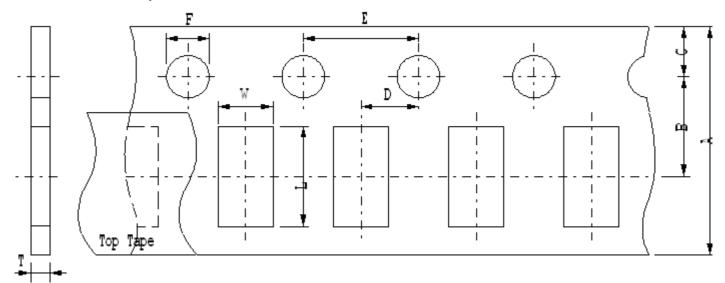
Operating temperature	-40 +125°C
Storage temperature (on board)	-40 +125°C
Response time	<1 ns
Solderability	245±5°C, 3 +0/-0.5sec
Solder leach resistance	260±5°C,10 ±1sec

5.2. Environmental Specifications

Storage Time: 12 months max. Storage Temperature: 5 to 40°C Relative Humidity: 65% max.

6. Taping Package and Label Marking

6.1. Carrier tape dimensions



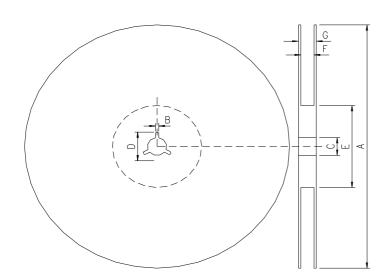
Α	В	С	D	E	F	L	Т	W
8.00±	3.50±	1.75±	2.00±	4.00±	1.50±	3.50±	0.95±	1.90±
0.30	0.05	0.10	0.05	0.10	0.10	0.15	0.05	0.15

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6.2. Taping reel dimensions



	UNIT: mm
Α	178.0±2.0
В	2.0±0.5
C	13.0±0.5
D	21.0±0.8
Е	62.0±1.5
F	9.0±0.5
G	13.0±1.0

6.3. Taping specifications

There shall be the portion having no product in both the head and the end of taping, and there shall be the cover tape in the head of taping.

6.4. Label Marking

The label specified as follows shall be put on the side of reel.

- (1) Part No.
- (2) Quantity
- (3) Lot No.

Part No. And Quantity shall be marked on outer packaging.

6.5. Quantity of products in the taping package

- (1) Standard quantity: 4000pcs/Reel for MLVS1206L series
- (2) Shipping quantity is a multiple of standard quantity.



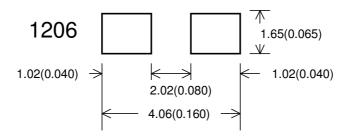
7. Precautions for Handling

7.1. Solder cream in reflow soldering

Refer to the recommendable land pattern as printing mask pattern for solder cream.

(1) Print solder in a thickness of 150 to 200 μm

Dimensions: millimeters (inches)



7.2. Precaution for handling of substrate

Do not exceed to bend the board after soldering this product extremely. (Reference examples)

- Mounting place must be as far as possible from the position, which is close to the break line of board, or on the line of large holes of board.
- Do not bend extremely the board, in mounting another component.

 If necessary, use back-up pin (support pin) to prevent from bending extremely.
- Do not break the board by hand. We recommend using the machine or the jig to break it.

7.3. Precaution for soldering

Note that rapid heating, rapid cooling or local heating will easily damage the component.

Do not give heat shock over 100°C in the process of soldering. We recommend taking preheating and gradual cooling.

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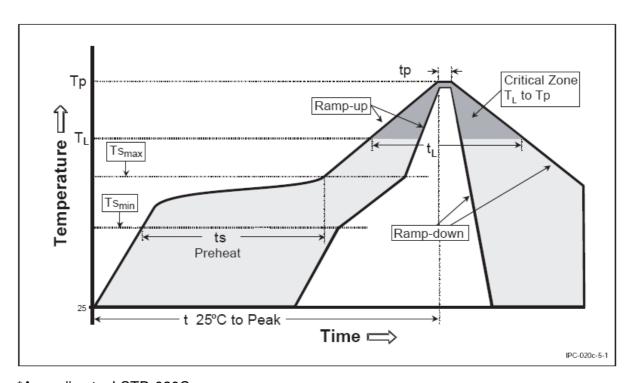
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7.4. Recommendable reflow soldering

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate	3°C/second max.
(Tsmax to Tp)	
Preheat	
– Temperature Min (Tsmin)	150℃
– Temperature Max (Tsmax)	200℃
Time (tsmin to tsmax)	60-180 seconds
Time maintained above:	
Temperature (TL)	217℃
- Time (tL)	60-150 seconds
Peak/Classification Temperature (Tp)	260℃
Time within 5 ℃ of actual Peak	
Temperature (tp)	20-40 seconds
Ramp-Down Rate	6°C/second max.
Time 25 ℃ to Peak Temperature	8 minutes max.



^{*}According to J-STD-020C

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7.5. Solder gun procedure

Note the follows, in case of using solder gun for replacement.

- (1) Use solder tip temperature must be less than 350°C for the period within 3 seconds by using soldering gun under 30W.
- (2) Soldering gun tip shall not touch component directly.

7.6. Soldering volume

Apply proper volume of solder paste, too much may cause crack of component body.

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